

DESIGN/PROCESS CHANGE NOTIFICATION

This is to inform you that a change is being made to the following products.

This is a minor change that has no impact on product quality, reliability, electrical or mechanical performance. Affected products will remain fully compliant to all published specifications. Notification is being made for informational purposes only and there is no approval required. Products incorporating this change may be shipped interchangeably with existing unchanged products.

Please contact your local Customer Quality Engineer if you have any questions regarding this notification. Alternatively, you may send an email request for information to PCNSupport@fairchildsemi.com.

Implementation of change:

Expected First Shipment Date for Changed Product : May. 02, 2012

Expected First Date Code of Changed Product : 1220

Description of Change (From) :

Strip mark position from heatsink side.



Before molding



After molding

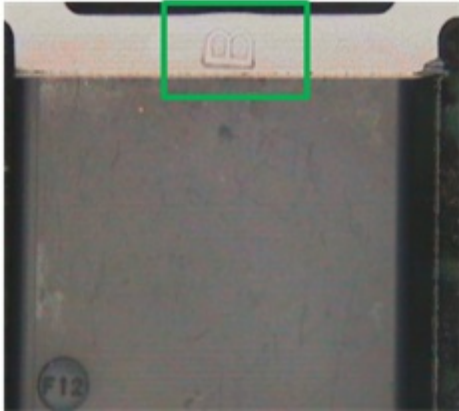


After TnF



Description of Change (To) :

Strip mark position to heatsink area.



Reason for Change:

This is for process control improvement (mixing prevention) in conjunction with the yield improvement.

Changing the position will eliminate this yield loss of about 2% and also provide traceability of units in terms mixing control.

As a background, this strip marking process is to prevent mixing and easy identification of leadframes of the lot. This strip mark will only be applied to 1 unit per strip. (1 strip = 40 units)

Affected Product(s):

FFB20UP20DN_F085	FFB20UP20DN_SB82195	FFB20UP20DN_SB82216
FQB12P20TM_SB82075	FQB25N33TM_NB82122	FQB34P10TM_F085
FQB7P20TM_F085	HGT1S7N60A4DS9A_SB82213	